

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0438600003

Status:

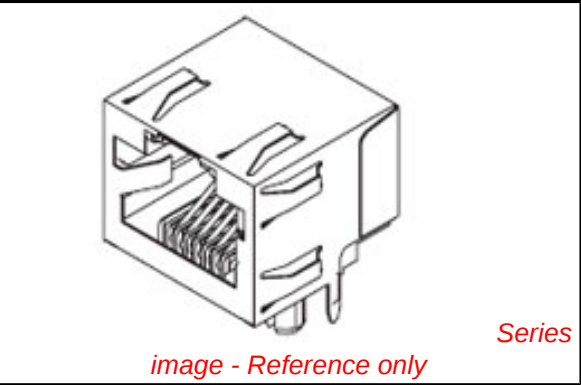
Active

Overview:

modular_plugs_jacks

Description:

Modular Jack, Right Angle, Low Profile, Inverted, 6/4



Documents:

3D Model

Drawing (PDF)

Application Specification (PDF)

Product Specification PS-43860-003 (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification

CSA

LR19980

UL

E107635

General

Product Family

Modular Jacks/Plugs

Series

43860

Component Type

PCB Jack

Magnetic

No

Overview

modular_plugs_jacks

Performance Category

3

Power over Ethernet (PoE)

N/A

Product Name

RJ11

Physical

Boot Color

N/A

Color - Resin

Black

Durability (mating cycles max)

500

Flammability

94V-0

Inverted / Top Latch

Yes

Lightpipes/LEDs

None

Material - Metal

Phosphor Bronze

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Orientation

Right Angle (Side Entry)

PCB Locator

Yes

PCB Retention

Yes

PCB Thickness Recommended (in)

0.062 In

PCB Thickness Recommended (mm)

1.60 mm

Packaging Type

Tube

Pitch - Mating Interface (in)

0.050 In

Pitch - Mating Interface (mm)

1.27 mm

Plating min: Mating (µin)

50

Plating min: Mating (µm)

1.25

Plating min: Termination (µin)

100

Plating min: Termination (µm)

2.5

Ports

1

Positions / Loaded Contacts

6/4

Surface Mount Compatible (SMC)

No

Temperature Range - Operating

-40°C to +85°C

Termination Interface: Style

Through Hole

Waterproof / Dustproof

No

Wire/Cable Type

N/A

Electrical

EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

Not Halogen-Free

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com

For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

43860Series

Mates With

FCC 68 Plugs

Current - Maximum per Contact	1.5A
Shielded	No
Voltage - Maximum	150V AC (RMS)
Solder Process Data	
Lead-free Process Capability	Wave Capable (TH only)

Material Info

Reference - Drawing Numbers

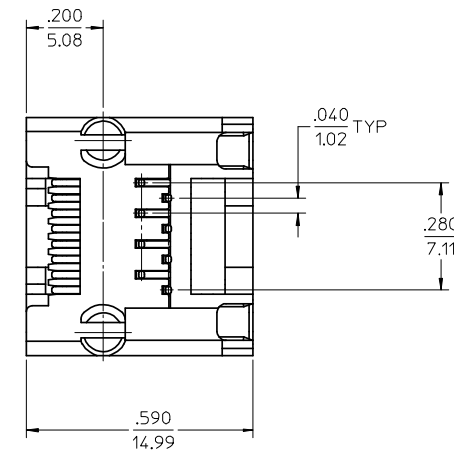
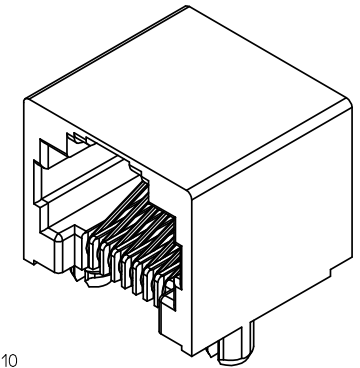
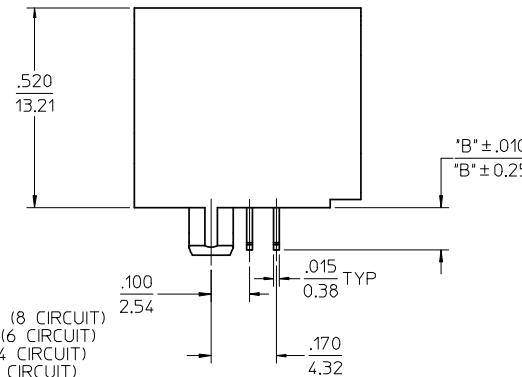
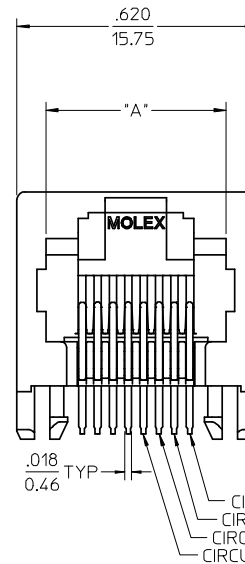
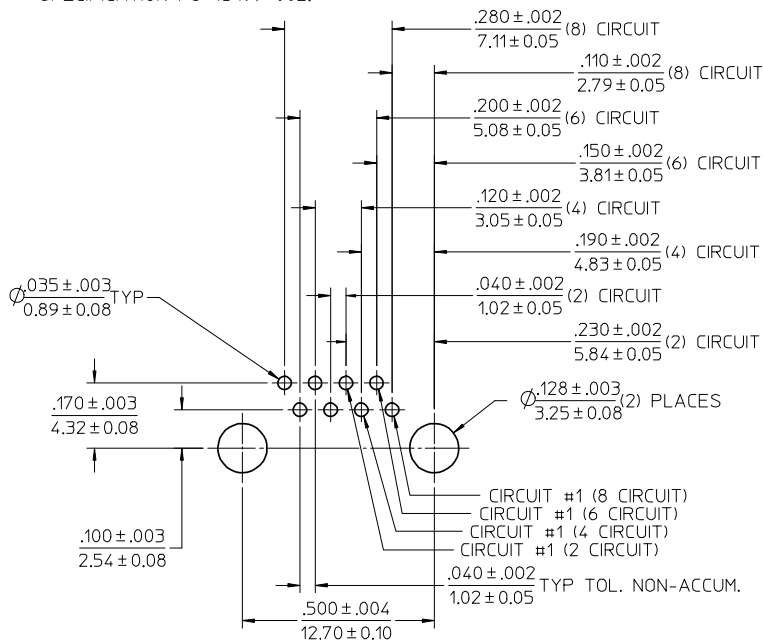
Packaging Specification	PK-43860-004
Product Specification	PS-43860-003, RPS-43860-004, RPS-43860-007, RPS-43860-008, RPS-43860-013
Sales Drawing	SD-43860-001, SD-43860-013
Test Summary	TS-43860-001

This document was generated on 06/07/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

NOTES:

- 1) MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE CHART
TERMINALS: PHOSPHOR BRONZE
- 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO
RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE
2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT
WITH TIN-LEAD IN THE PC TAILS.
- 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
- 4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX
PACKAGING SPECIFICATION PK-43860-004.
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



ASSEMBLY MAT. NUM.	CONNECTOR SIZE	DIM "A"	DIM "B"	CIRCUITS	HOUSING COLOR
43860-0001	8	.469/11.91	.110/2.79	8	BLACK
43860-2001	8	.469/11.91	.080/2.03	8	BLACK
43860-0002	6	.389/9.88	.110/2.79	6	BLACK
43860-0003	6	.389/9.88	.110/2.79	4	BLACK
43860-0019	8	.469/11.91	.110/2.79	4	BLACK
43860-0020	6	.389/9.88	.110/2.79	2	BLACK

ADD PART #, SHT 2
EC NO: UCP2008-3111
DRAWN: SCHMIDT 2008/06/20
CHKD: JEBEL 2008/06/27
APPR: FSMITH 2008/07/14
REV

QUALITY
SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES ±	---	---
3 PLACES ±	---	±.010
2 PLACES ±	±0.25	---
1 PLACE ±	---	---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
IN/MM

DRAWN BY	DATE
TALEND	1997/02/13
CHECKED BY	DATE
ROBERTS	1997/03/03
APPROVED BY	DATE
FRY	1997/03/04

MATERIAL NO.
SEE CHART

SIZE
C

SCALE
4:1

DESIGN UNITS
INCH

THIRD ANGLE
PROJECTION

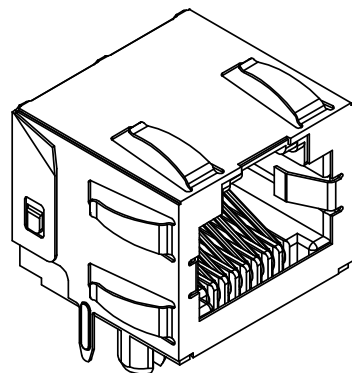
TITLE
INVERTED MODULAR JACK
ASSEMBLY

MOLEX INCORPORATED

DOCUMENT NO.
SD-43860-001

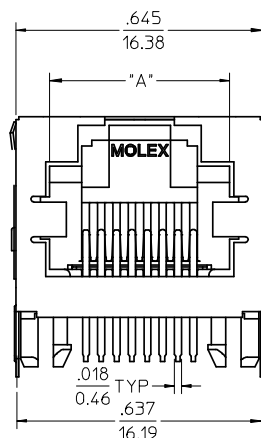
SHEET NO.
1 OF 5

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

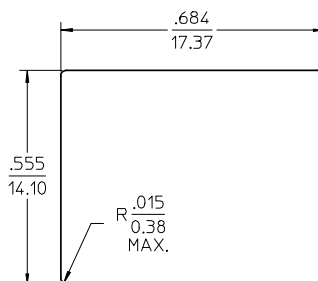


NOTES:

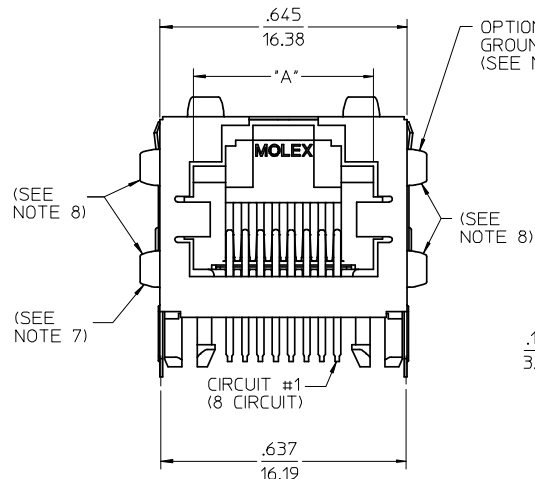
- 1) MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0,
COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
SHIELD: BRASS
- 2) FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES/
1.27 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES/
2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES/
1.27 MICROMETERS MIN.
SHIELD:
*100 MICROINCHES/2.54 MICROMETERS NICKEL OVER
50 MICROINCHES/1.27 MICROMETERS COPPER
UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED
"COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND
ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN
PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
- 3) PRODUCT SPECIFICATION: PS-43860-003.
- 4) PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS
PER MOLEX PACKAGING SPECIFICATION PK-43860-005.
43860-5025 CONNECTOR ASSEMBLIES PACKAGED IN TAPE AND
REEL PER MOLEX PACKAGING SPECIFICATION PK-70873-700*
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 7) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS
OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY
MATERIAL NUMBER TABLE.
- 8) AVAILABLE WITH TOP PANEL GROUND TABS ONLY, PER THE
ASSEMBLY MATERIAL NUMBER TABLE.
- 9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



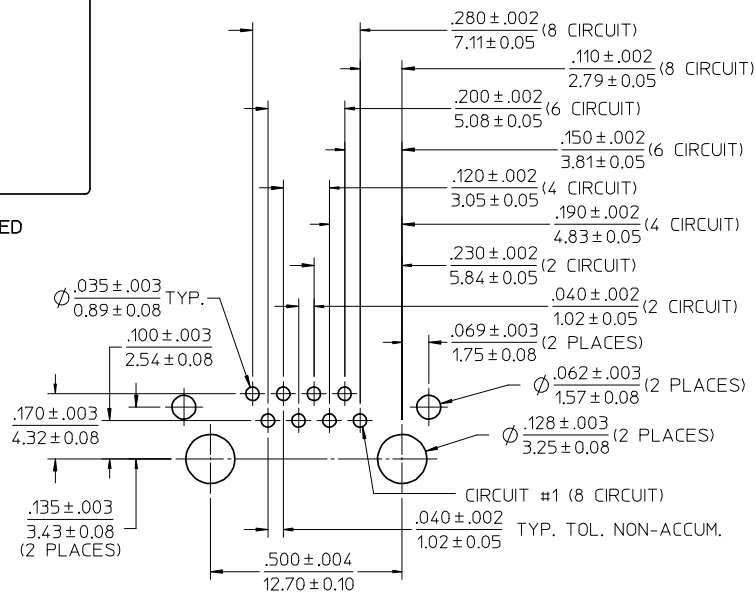
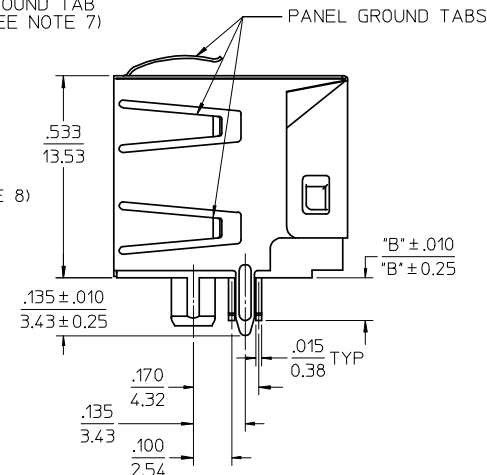
NO PANEL
GROUND TABS



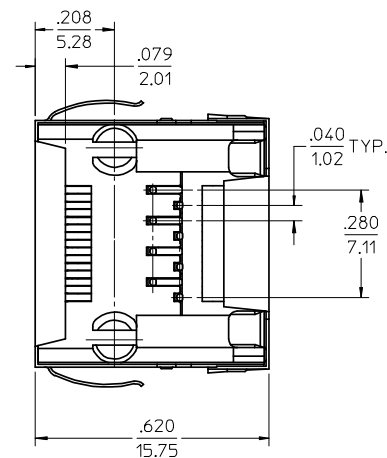
RECOMMENDED
PANEL
OPENING



OPTIONAL PANEL
GROUND TAB
(SEE NOTE 7)



PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PCB THICKNESS .062 ± .005/1.57 ± 0.13



ASSEMBLY MAT. NUM.	CONNECTOR SIZE	DIM "A"	DIM "B"	CIRCUITS	PANEL GROUND TABS	PACKAGING OPTION
43860-0004	8	.469/11.91	.110/2.79	8	ALL	TRAY
43860-2004	8	.469/11.91	.080/2.03	8	ALL	TRAY
43860-0005	6	.389/9.88	.110/2.79	6	ALL	TRAY
43860-0006	6	.389/9.88	.110/2.79	4	ALL	TRAY
43860-0013	8	.469/11.91	.110/2.79	8	SEE NOTE #7	TRAY
43860-0014	6	.389/9.88	.110/2.79	6	SEE NOTE #7	TRAY
43860-0015	6	.389/9.88	.110/2.79	4	SEE NOTE #7	TRAY
43860-0024	6	.389/9.88	.110/2.79	2	ALL	TRAY
43860-0025	8	.469/11.91	.110/2.79	8	NONE	TRAY
43860-0026	6	.389/9.88	.110/2.79	6	NONE	TRAY
43860-0027	6	.389/9.88	.110/2.79	4	NONE	TRAY
43860-0031	8	.469/11.91	.110/2.79	8	SEE NOTE #8	TRAY
43860-5025	8	.469/11.91	.110/2.79	8	NONE	TAPE

ADD 43860-5025
EC NO: UCP2008-3111
DRAWN: SCHMIDT 2008/06/20
CHKD: JEBEL 2008/06/27
APPR: FSM/TH 2008/07/14
REV H6

QUALITY
SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES ±	---	---
3 PLACES ±	---	±.010
2 PLACES ±	0.25	---
1 PLACE ±	---	---

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
IN/MM

DRAWN BY	DATE
TALEND	1997/02/13
CHECKED BY	DATE
ROBERTS	1997/03/03
APPROVED BY	DATE
FRY	1997/03/04

MATERIAL NO.
SEE CHART

SIZE
C

SCALE
4:1

DESIGN UNITS
INCH

THIRD ANGLE
PROJECTION

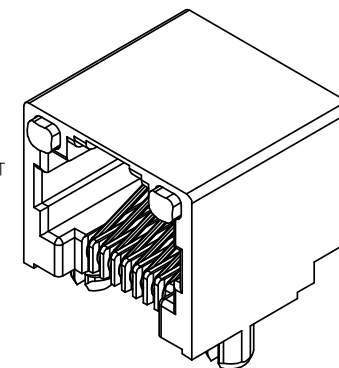
INVERTED MODULAR JACK
ASSEMBLY

MOLEX INCORPORATED

DOCUMENT NO.
SD-43860-001

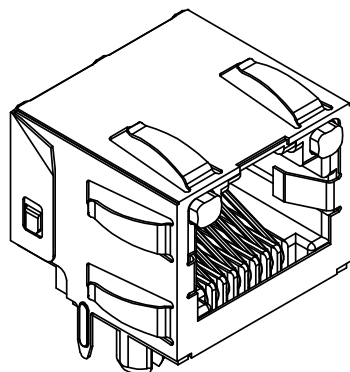
SHEET NO.
2 OF 5

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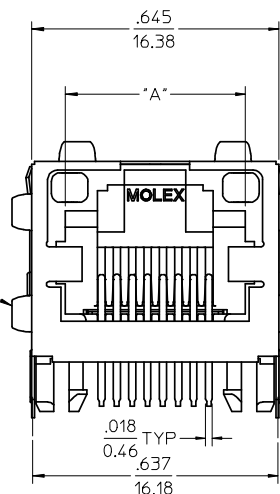


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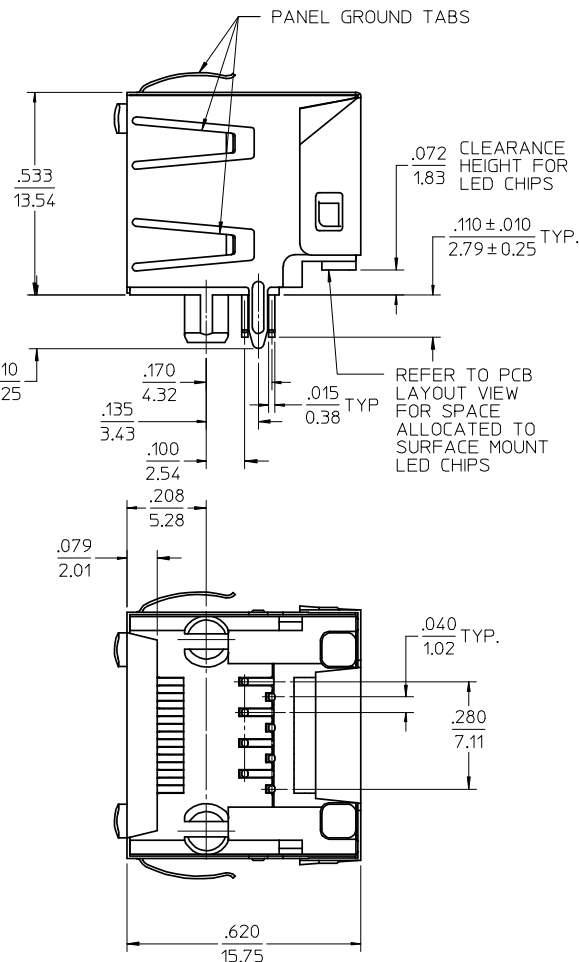
SEE SHEET 1 EC NO: UCP2008-3111 DWG: INCL SDMI DT CHKD: JBELM APPR: FSMITH 2008/06/20 2008/06/27 2008/07/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	
	=0 =0		mm	INCH	DRAWN BY	DATE	TITLE INVERTED MODULAR JACK ASSEMBLY		
		4 PLACES	± ---	± ---	TALEND	1997/02/13			
		3 PLACES	± ---	± .010	CHECKED BY	DATE			
		2 PLACES	± 0.25	± ---	ROBERTS	1997/03/03			
	1 PLACE	± ---	± ---	APPROVED BY	DATE	MOLEX MOLEX INCORPORATED			
	ANGULAR ±1/2°		FRY	1997/03/04					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO. SEE CHART		DOCUMENT NO. SD-43860-001		SHEET NO. 3 OF 5
H6 REV		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



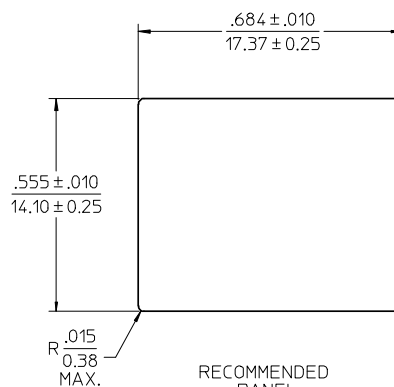
OPTIONAL PANEL
GROUND TAB
(SEE NOTE 8)



OPTIONAL PANEL
GROUND TAB
(SEE NOTE 8)



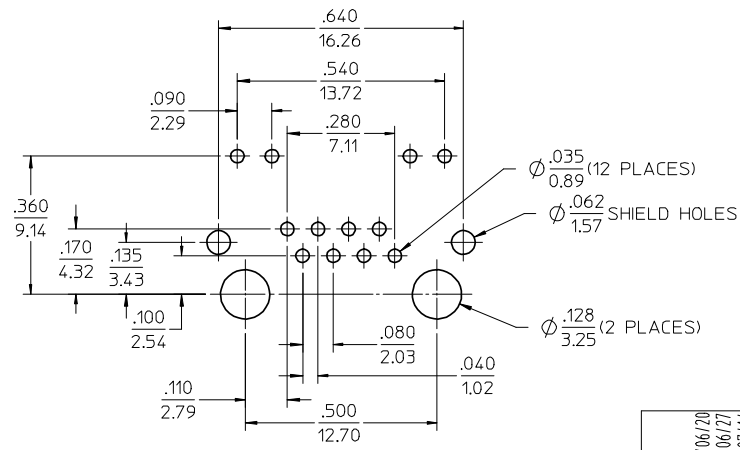
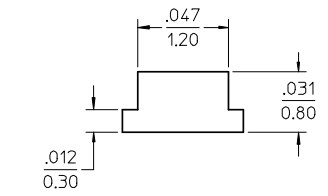
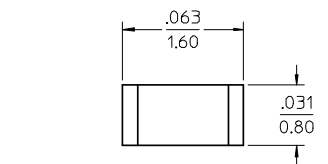
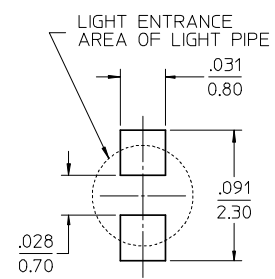
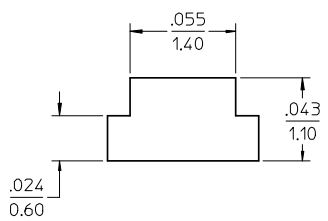
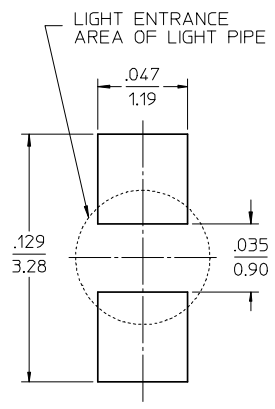
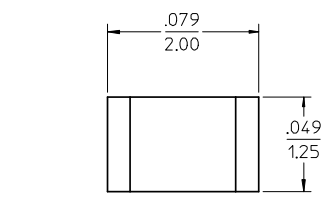
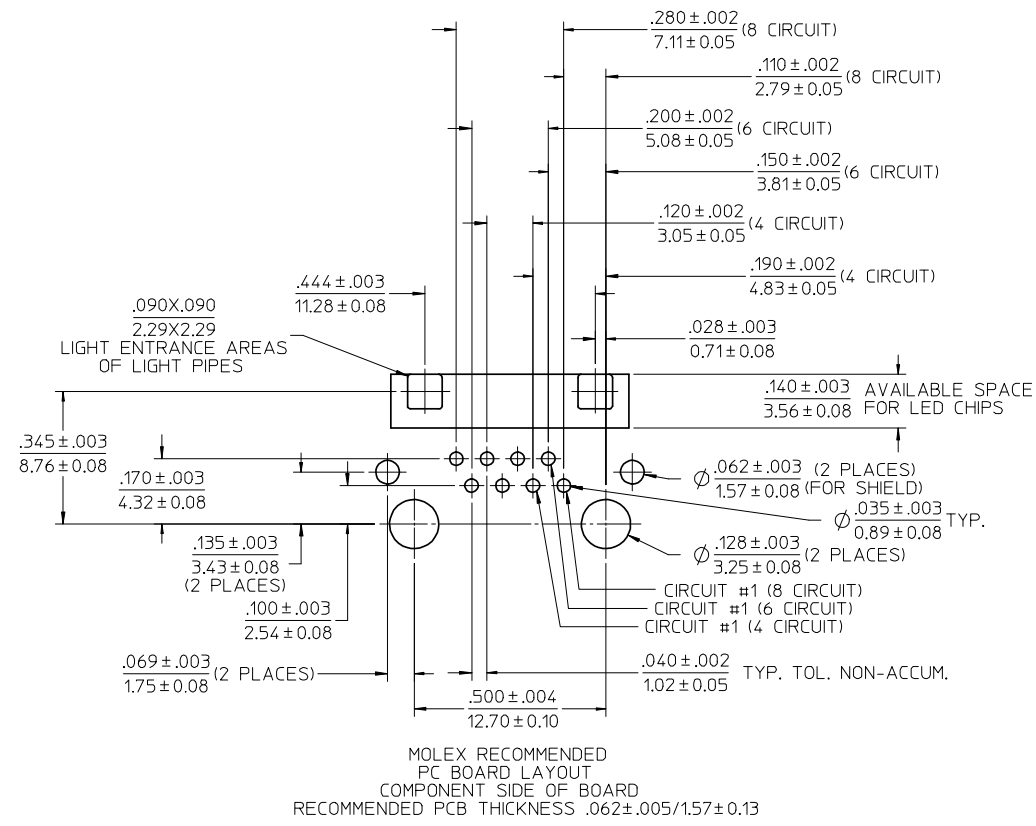
- NOTES:
- MATERIAL:
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE
SHIELD: BRASS
LIGHT PIPES:
POLYCARBONATE - WAVE OR HAND SOLDER ONLY
(NOT DESIGNED FOR I/R REFLOW OR
CONVECTION REFLOW SOLDER PROCESSES).
POLYSULFONE - MAXIMUM REFLOW TEMPERATURE 400°F (205°C)
 - FINISH:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES/1.27 MICROMETERS MIN.,
*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES/2.54 MICROMETERS MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES/1.27 MICROMETERS MIN.
SHIELD:
*100 MICROINCHES/2.54 MICROMETERS OVER 50 MICROINCHES/1.27
MICROMETERS COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS
DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC".
CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN
THE PC TAILS AND/OR SHIELD.
 - PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
 - PACKAGING SPECIFICATION:
CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX
PACKAGING SPECIFICATION PK-43860-005.
 - APPLICATION SPECIFICATION: AS-43860-001
 - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
 - CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
 - AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE
TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
 - REFER TO SHEET (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



RECOMMENDED
PANEL
OPENING

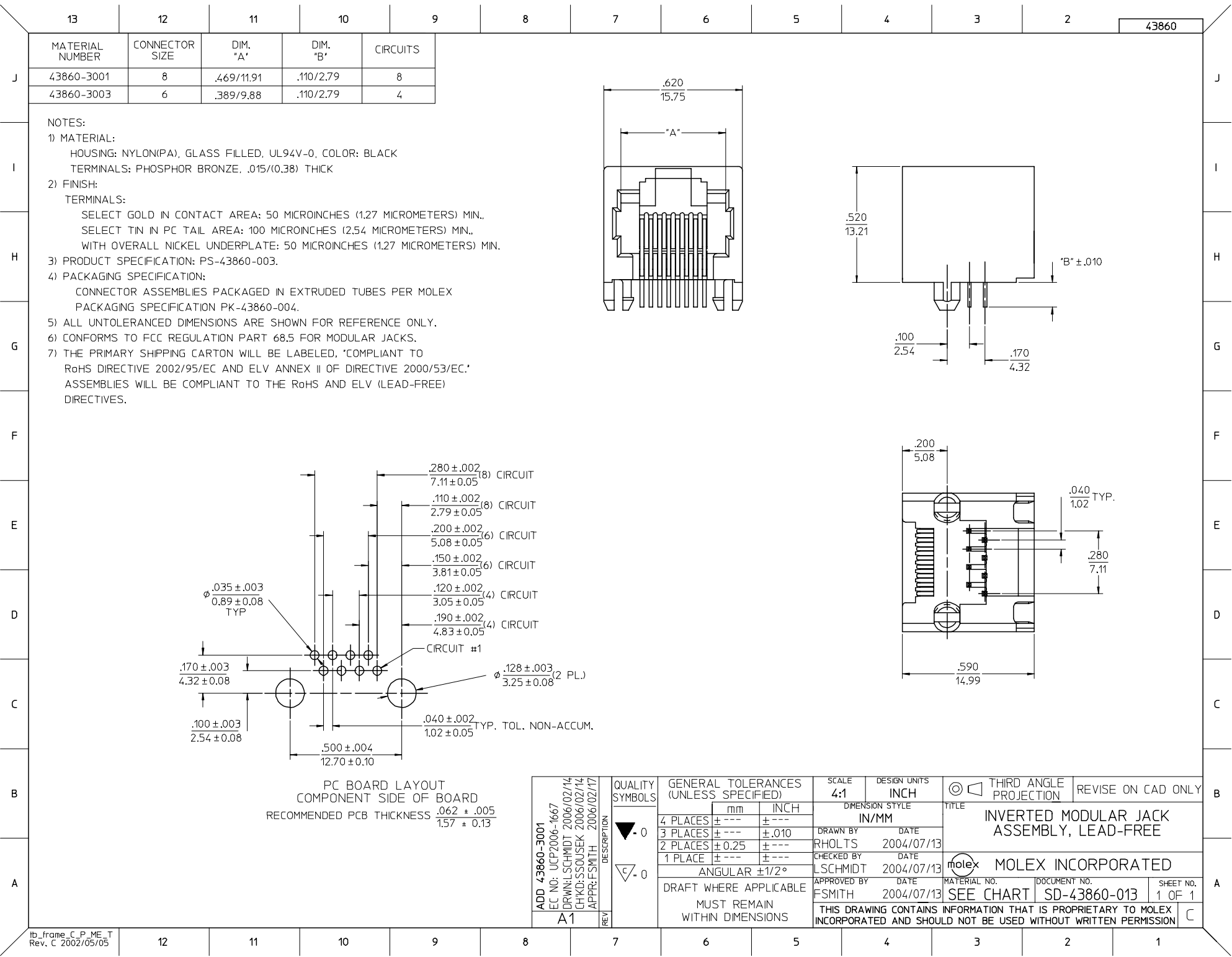
ASSEMBLY MAT. NUM.	LIGHT PIPE MATERIAL	CONNECTOR SIZE	DIM "A"	CIRCUITS	PANEL GROUND TABS
43860-0010	POLYCARBONATE	8	.469/11.91	8	ALL
43860-0011	POLYCARBONATE	6	.389/9.88	6	ALL
43860-0012	POLYCARBONATE	6	.389/9.88	4	ALL
43860-0016	POLYCARBONATE	8	.469/11.91	8	SEE NOTE #8
43860-0017	POLYCARBONATE	6	.389/9.88	6	SEE NOTE #8
43860-0018	POLYCARBONATE	6	.389/9.88	4	SEE NOTE #8
43860-1010	POLYSULFONE	8	.469/11.91	8	ALL
43860-1011	POLYSULFONE	6	.389/9.88	6	ALL
43860-1012	POLYSULFONE	6	.389/9.88	4	ALL
43860-1016	POLYSULFONE	8	.469/11.91	8	SEE NOTE #8
43860-1017	POLYSULFONE	6	.389/9.88	6	SEE NOTE #8
43860-1018	POLYSULFONE	6	.389/9.88	4	SEE NOTE #8

SEE SHEET 1 EC NO: UCP2008-3111 DRAWN: SCHMIDT CHKD: JEBEL APPR: FSM/TH H6	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± ---	DRAWN BY TALEND	DATE 1997/02/13	TITLE INVERTED MODULAR JACK ASSEMBLY		
		3 PLACES ± --- ± .010	CHECKED BY ROBERTS	DATE 1997/03/03			
		2 PLACES ± .025 ± ---	APPROVED BY FRY	DATE 1997/03/04			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO. SEE CHART	DOCUMENT NO. SD-43860-001	SHEET NO. 4 OF 5		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



NOTES:
1. FOR CROSS REFERENCE OF RECOMMENDED LED'S SEE MOLEX WEB SITE

SEE SHEET 1 EC NO: UCP2008-3111 DRAWN: SCHMIDT 2008/06/20 CHKD: JEBEL 2008/06/27 APPR: FSMITH 2008/07/14 H6	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	 THIRD ANGLE PROJECTION	TITLE INVERTED MODULAR JACK ASSEMBLY	
				mm	INCH	DRAWN BY TALEND	DATE 1997/02/13	DOCUMENT NO. SD-43860-001			SHEET NO. 5 OF 5
			4 PLACES	± ---	± ---	CHECKED BY ROBERTS	DATE 1997/03/03				
			3 PLACES	± ---	± .010	APPROVED BY FRY	DATE 1997/03/04				
			2 PLACES	± ---	± 0.25	MATERIAL NO. SEE CHART					
			1 PLACE	± ---	± ---						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			ANGULAR ±1/2°		MOLEX MOLEX INCORPORATED						
REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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